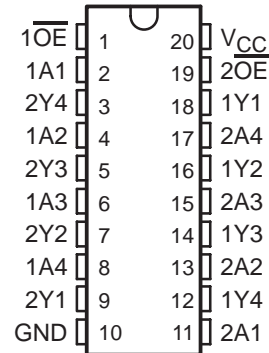


SN54BCT244, SN74BCT244 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS006E – OCTOBER 1987 – REVISED APRIL 1994

- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- P-N-P Inputs Reduce DC Loading
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic and Ceramic 300-mil DIPs (J, N)

SN54BCT244 . . . J OR W PACKAGE
SN74BCT244 . . . DB OR DW OR N PACKAGE
(TOP VIEW)



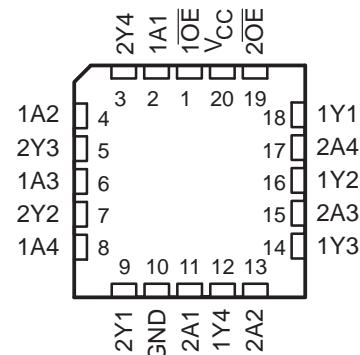
description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Taken together with the 'BCT240 and 'BCT241, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical \overline{OE} (active-low output-enable) inputs, and complementary OE and \overline{OE} inputs.

The 'BCT244 is organized as two 4-bit buffers/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

The SN54BCT244 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74BCT244 is characterized for operation from 0°C to 70°C .

SN54BCT244 . . . FK PACKAGE
(TOP VIEW)



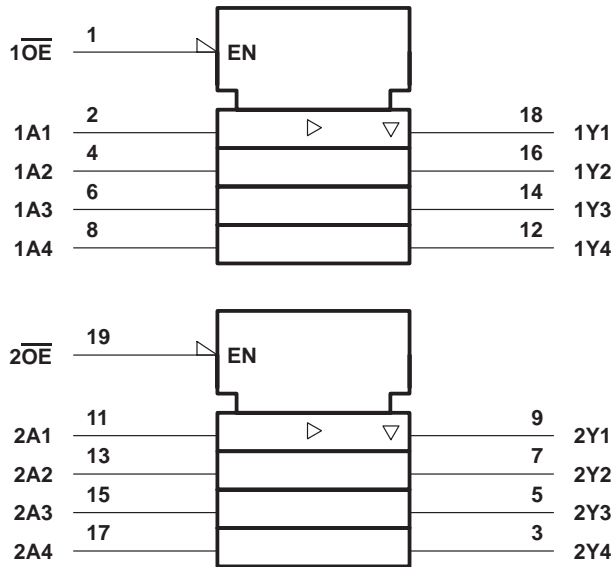
FUNCTION TABLE
(each buffer)

| INPUTS | | OUTPUT |
|-----------------|---|--------|
| \overline{OE} | A | Y |
| L | H | H |
| L | L | L |
| H | X | Z |

SN54BCT244, SN74BCT244 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

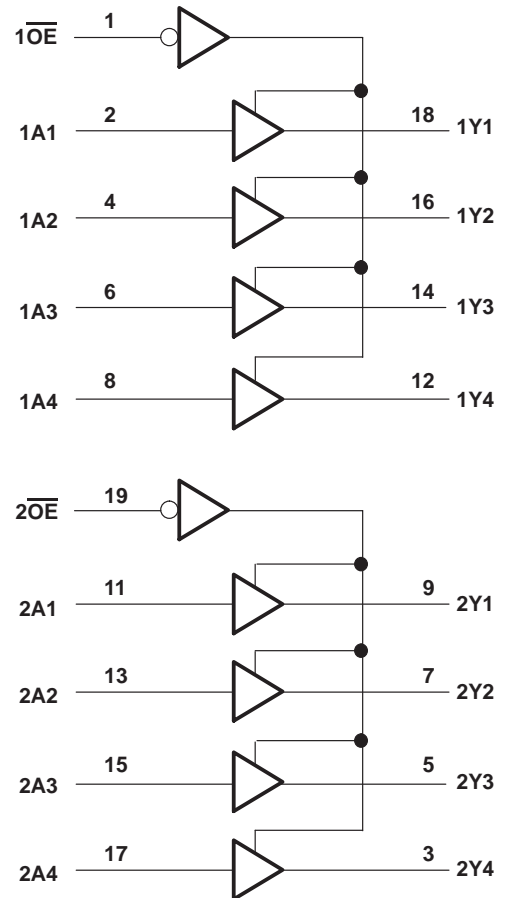
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

| | |
|---|---------------------|
| Supply voltage range, V_{CC} | - 0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | - 0.5 V to 7 V |
| Voltage range applied to any output in the disabled or power-off state, V_O | - 0.5 V to 5.5 V |
| Voltage range applied to any output in the high state, V_{OH} | - 0.5 V to V_{CC} |
| Current into any output in the low state: SN54BCT244 | 96 mA |
| SN74BCT244 | 128 mA |
| Operating free-air temperature range: SN54BCT244 | - 55°C to 125°C |
| SN74BCT244 | 0°C to 70°C |
| Storage temperature range | - 65°C to 150°C |

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.



SN54BCT244, SN74BCT244 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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recommended operating conditions

| | | SN54BCT244 | | | SN74BCT244 | | | UNIT |
|----------|--------------------------------|------------|-----|-----|------------|-----|-----|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| V_{CC} | Supply voltage | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| V_{IH} | High-level input voltage | 2 | | | 2 | | | V |
| V_{IL} | Low-level input voltage | | | 0.8 | | | 0.8 | V |
| I_{IK} | Input clamp current | | | -18 | | | -18 | mA |
| I_{OH} | High-level output current | | | -12 | | | -15 | mA |
| I_{OL} | Low-level output current | | | 48 | | | 64 | mA |
| T_A | Operating free-air temperature | -55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | SN54BCT244 | | | SN74BCT244 | | | UNIT |
|-------------------|--|------------|------|------|------------|------|------|------|
| | | MIN | TYP† | MAX | MIN | TYP† | MAX | |
| V_{IK} | $V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$ | | | -1.2 | | | -1.2 | V |
| V_{OH} | $V_{CC} = 4.5\text{ V}$ | | | 2.4 | 3.3 | 2.4 | 3.3 | V |
| | | | | 2 | 3.2 | | | |
| | | | | | | 2 | 3.1 | |
| V_{OL} | $V_{CC} = 4.5\text{ V}$ | | | 0.38 | 0.55 | | | V |
| | | | | | | 0.42 | 0.55 | |
| I_I | $V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$ | | | 0.1 | | | 0.1 | mA |
| I_{IH} | $V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$ | | | 20 | | | 20 | μA |
| I_{IL} | $V_{CC} = 5.5\text{ V}$, $V_I = 0.5\text{ V}$ | | | -1 | | | -1 | mA |
| I_{OZH} | $V_{CC} = 5.5\text{ V}$, $V_O = 2.7\text{ V}$ | | | 50 | | | 50 | μA |
| I_{OZL} | $V_{CC} = 5.5\text{ V}$, $V_O = 0.5\text{ V}$ | | | -50 | | | -50 | μA |
| I_{OS}^\ddagger | $V_{CC} = 5.5\text{ V}$, $V_O = 0$ | -100 | | -225 | -100 | | -225 | mA |
| I_{CCH} | $V_{CC} = 5.5\text{ V}$, Outputs open | | 23 | 40 | | 23 | 40 | mA |
| I_{CCL} | $V_{CC} = 5.5\text{ V}$, Outputs open | | 53 | 80 | | 53 | 80 | mA |
| I_{CCZ} | $V_{CC} = 5.5\text{ V}$, Outputs open | | 4 | 10 | | 4 | 10 | mA |

† All typical values are at $V_{CC} = 5\text{ V}$.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.



SN54BCT244, SN74BCT244 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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switching characteristics (see Note 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 5 V, C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = 25°C | | | V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = MIN to MAX† | | | | UNIT |
|------------------|------------------------|----------------|--|-----|-----|--|-----|------------|-----|------|
| | | | 'BCT244 | | | SN54BCT244 | | SN74BCT244 | | |
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t _{PLH} | A | Y | 1.2 | 2.5 | 4.4 | 0.9 | 5.3 | 0.9 | 5 | ns |
| t _{PHL} | | | 1.7 | 3.2 | 5 | 1.4 | 6 | 1.4 | 5.5 | |
| t _{PZH} | $\overline{\text{OE}}$ | Y | 2 | 5.7 | 7.8 | 2 | 9 | 2 | 8.7 | ns |
| t _{PZL} | | | 2 | 5.9 | 8.1 | 2 | 9.4 | 2 | 8.9 | |
| t _{PHZ} | $\overline{\text{OE}}$ | Y | 2 | 5.4 | 6.7 | 2 | 8 | 2 | 7.7 | ns |
| t _{PLZ} | | | 2 | 6.1 | 7.6 | 2 | 9.8 | 2 | 8.9 | |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|--|-------------------------|
| 5962-9062501M2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962- 9062501M2A SNJ54BCT 244FK | Samples |
| 5962-9062501MRA | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9062501MR A SNJ54BCT244J | Samples |
| 5962-9062501MSA | ACTIVE | CFP | W | 20 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9062501MS A SNJ54BCT244W | Samples |
| SN74BCT244DBLE | OBSOLETE | SSOP | DB | 20 | | TBD | Call TI | Call TI | 0 to 70 | | |
| SN74BCT244DW | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | BCT244 | Samples |
| SN74BCT244DWE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | BCT244 | Samples |
| SN74BCT244DWG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | BCT244 | Samples |
| SN74BCT244DWR | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | BCT244 | Samples |
| SN74BCT244DWRE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | BCT244 | Samples |
| SN74BCT244DWRG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | BCT244 | Samples |
| SN74BCT244N | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN74BCT244N | Samples |
| SN74BCT244NE4 | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN74BCT244N | Samples |
| SN74BCT244NSR | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | BCT244 | Samples |
| SN74BCT244NSRE4 | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | BCT244 | Samples |
| SN74BCT244NSRG4 | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | BCT244 | Samples |
| SNJ54BCT244FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962- 9062501M2A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|-------------------------|----------------------|--------------|-------------------------------------|---------|
| | | | | | | | | | | SNJ54BCT 244FK | |
| SNJ54BCT244J | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9062501MR A SNJ54BCT244J | Samples |
| SNJ54BCT244W | ACTIVE | CFP | W | 20 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9062501MS A SNJ54BCT244W | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54BCT244, SN74BCT244 :

- Catalog: [SN74BCT244](#)
- Military: [SN54BCT244](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS

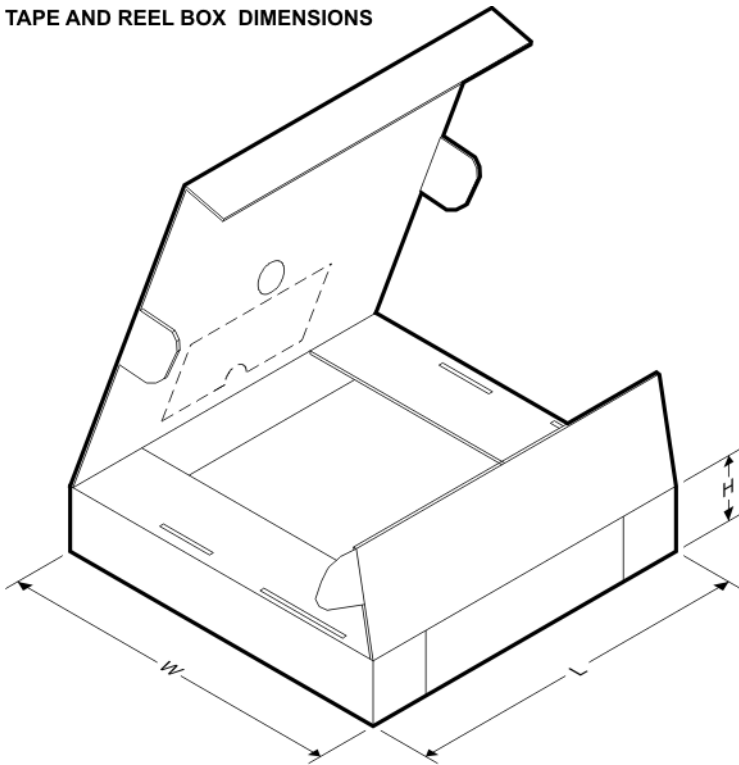


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74BCT244DWR | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| SN74BCT244NSR | SO | NS | 20 | 2000 | 330.0 | 24.4 | 8.2 | 13.0 | 2.5 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74BCT244DWR | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74BCT244NSR | SO | NS | 20 | 2000 | 367.0 | 367.0 | 45.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |

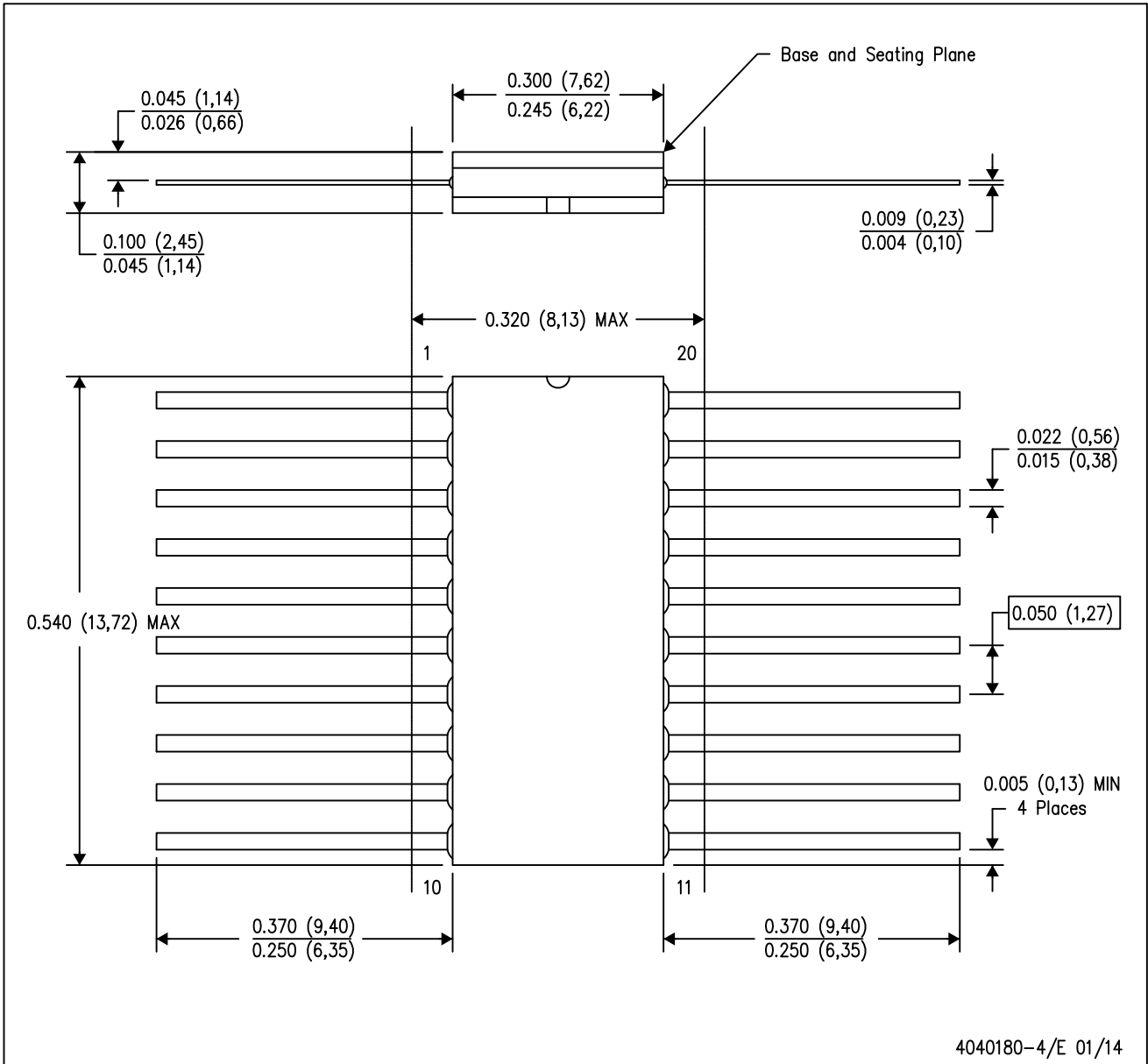


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



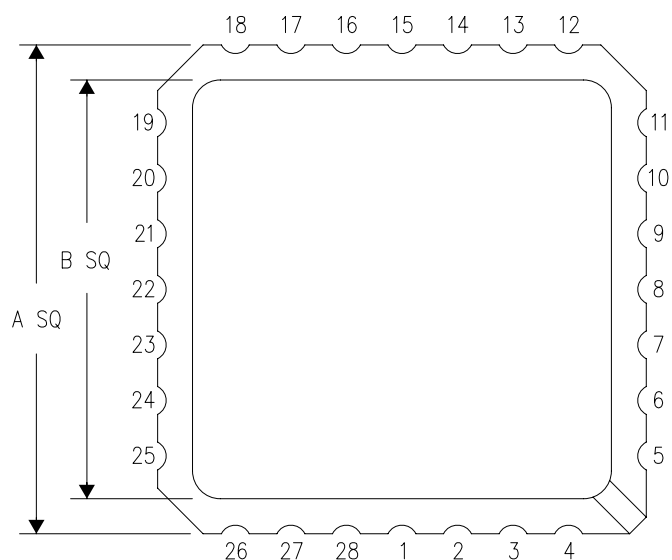
4040180-4/E 01/14

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

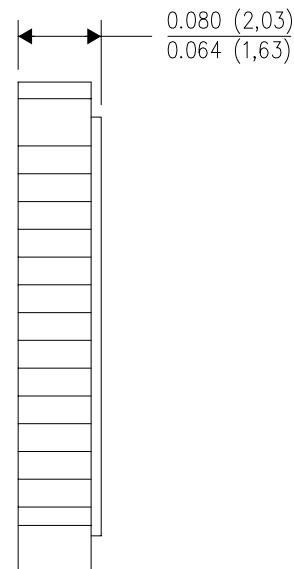
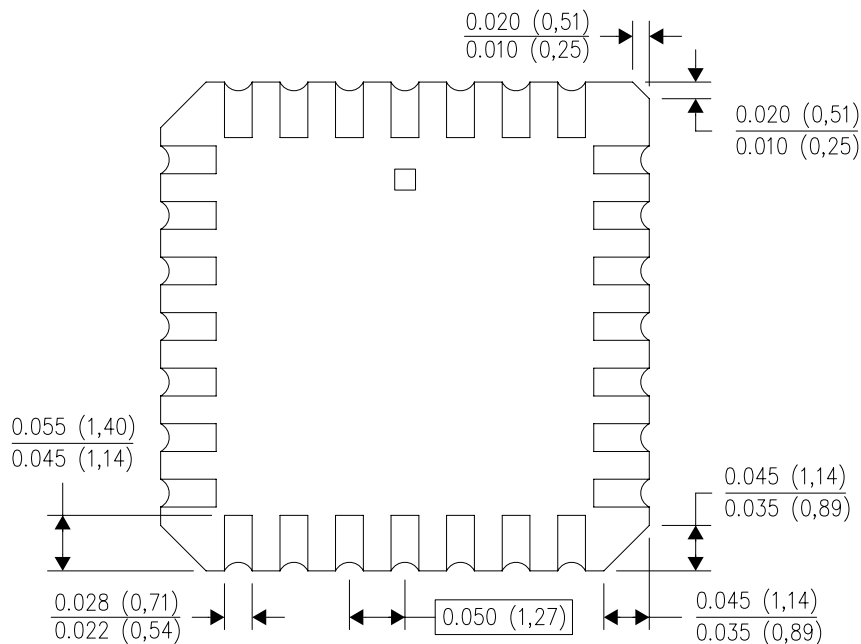
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF TERMINALS ** | A | | B | |
|---------------------|------------------|------------------|------------------|------------------|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

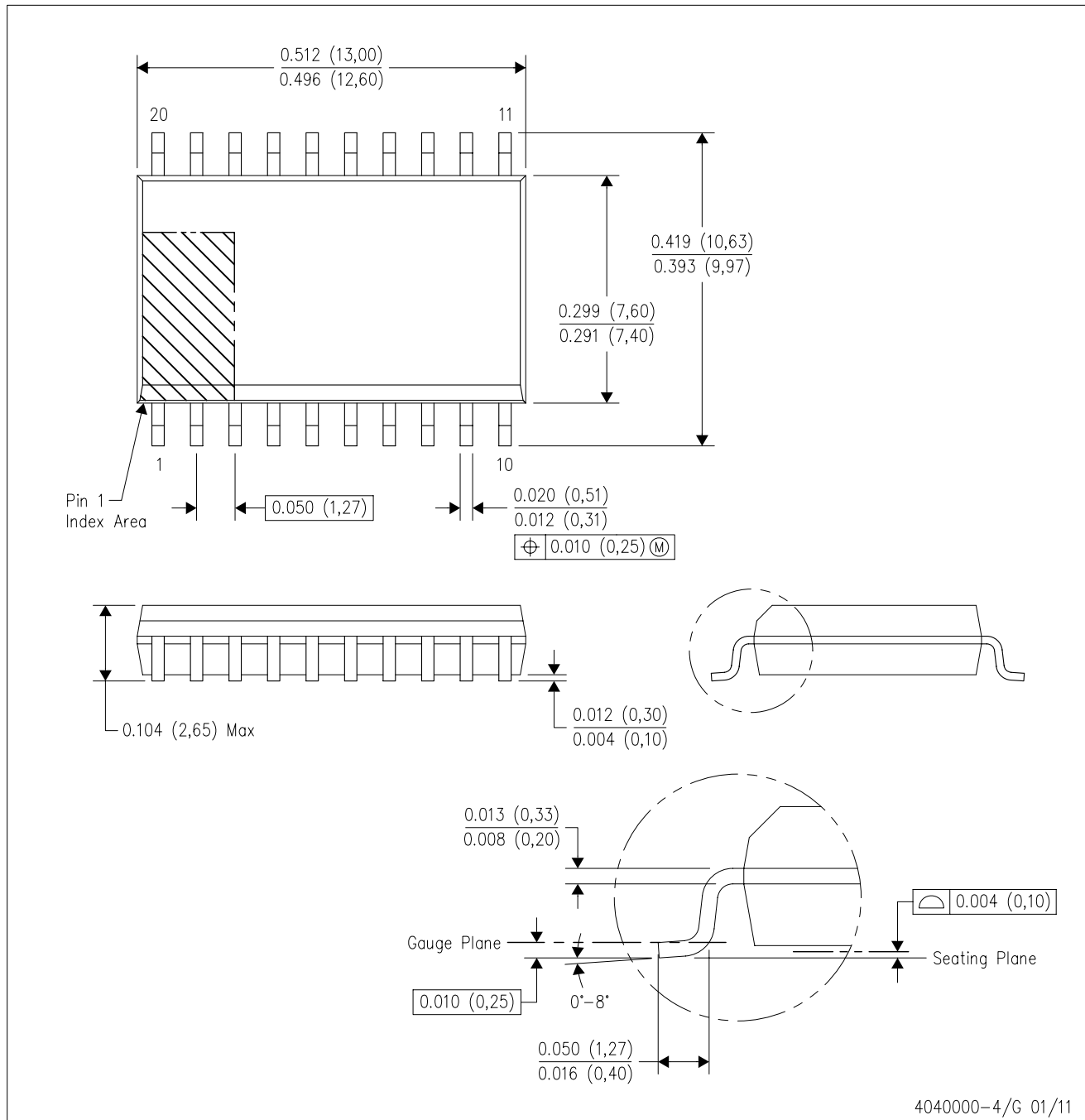


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

DW (R-PDSO-G20)

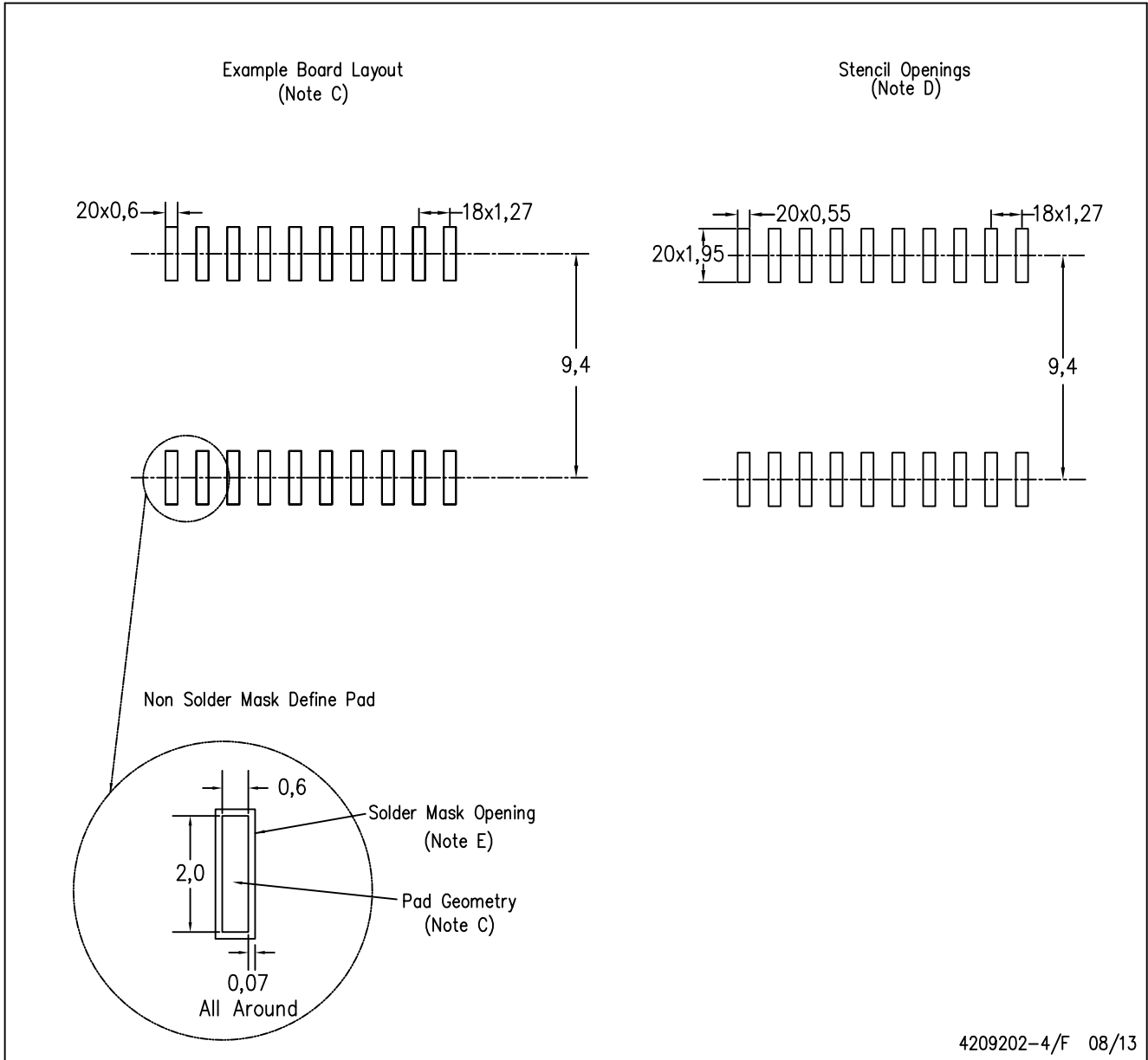
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4209202-4/F 08/13

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

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